



Wrocław
University
of Science
and Technology

VACUUM-SEALED ELECTRON BEAM MICROCOLUMN FOR HIGH VACUUM MEMS DEVICES

Michał Krysztof, Tomasz Grzebyk, Marcin Białas,
Paweł Urbański, Piotr Szyszka, Jan Sobków,
Jakub Jendryka, Michał Zychla

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VDE ITG 2024, Bad Honnef, August 29th 2024



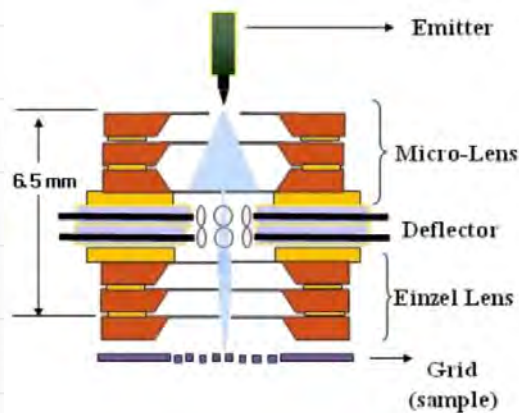
OUTLINE

1. Electron beam microcolumns – state-of-the-art
2. MEMS high vacuum micropump
3. MEMS electron beam microcolumn and its application
 - A. MEMS scanning electron microscope
 - B. MEMS point X-ray source
 - C. MEMS electron source
 - D. MEMS free electron laser
4. Summary

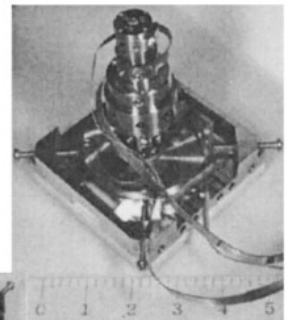
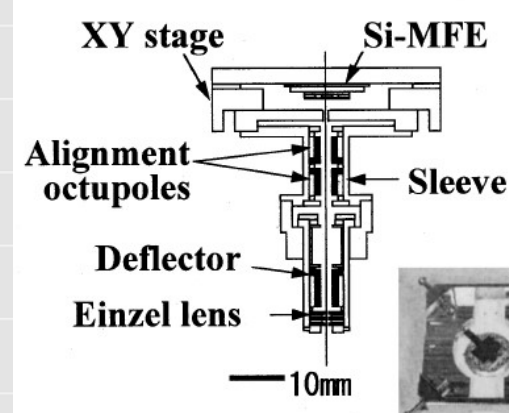


State-of-the-art

ELECTRON BEAM MICROCOLUMNS

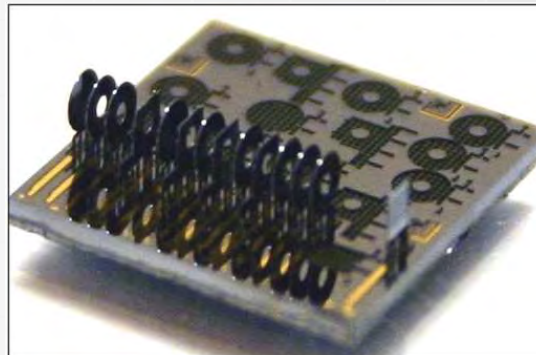


H. S. Kim et al., *The assembly of a fully functional microcolumn and its STEM-Mode operation*, Journal of the Korean Physical Society 43, 5 (2003) 831-835.

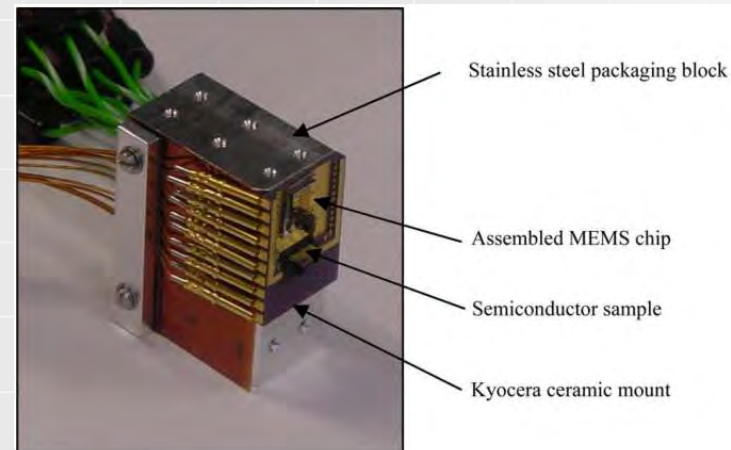


**Si-MFE gun
on XY stage**

I. Honjo et al., *Miniature electron beam column with a silicon micro field emitter*, J. Vac. Sci. Technol. B 15 (1997) 2742-2748.



R. Saini, et al., *Manufacturable MEMS miniSEMs*, Microelectronic Engineering 83 (2006) 1376-1381





State-of-the-art

ELECTRON BEAM MICROCOLUMNS

Fabrication methods:

- Precision mechanics
- Microelectronics and microengineering
- MEMS

Applications:

- X-ray sources
- Ion sources
- Lithography tools
- Imaging methods (SEM)

Parameters:

- Resolution < 50 nm
- High and stable electron beam
- High precision electron beam scanning

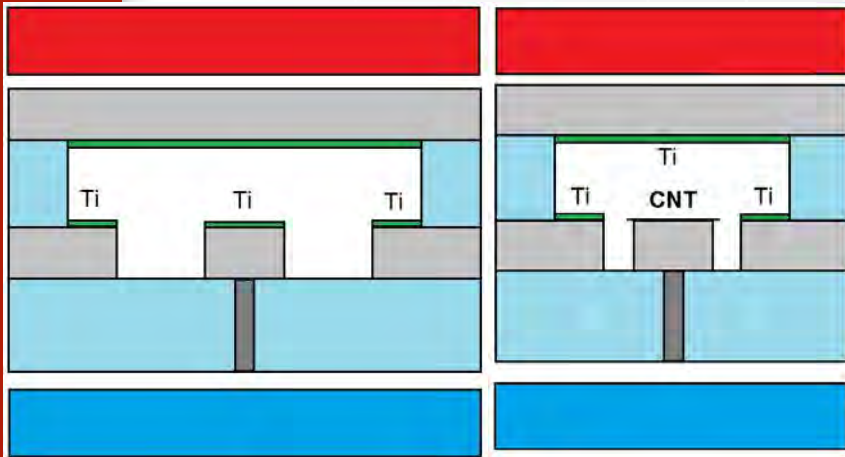
**NO PUMPING SYSTEM
DEVELOPED**



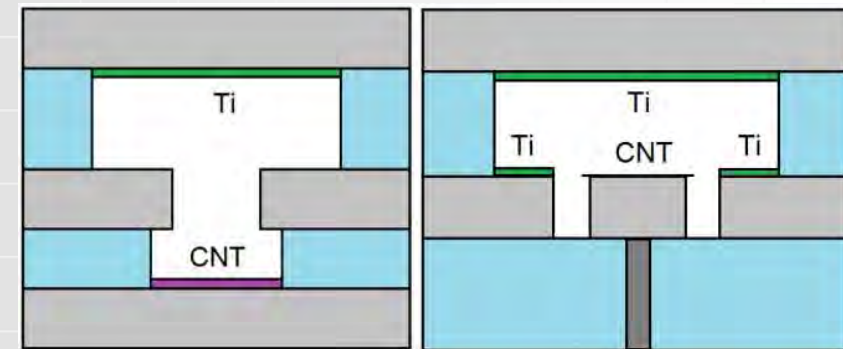
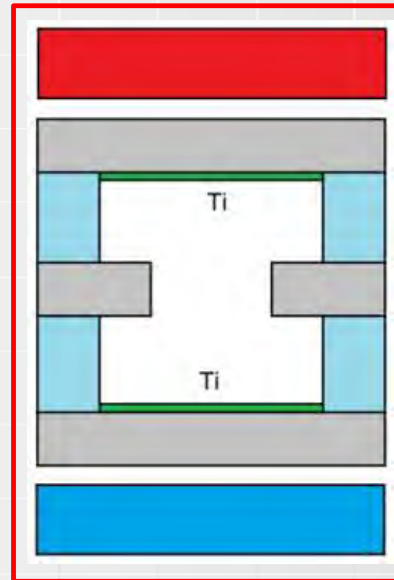
MEMS high vacuum micropump

Silicon-glass, anodically bonded ion-sorption vacuum micropumps:

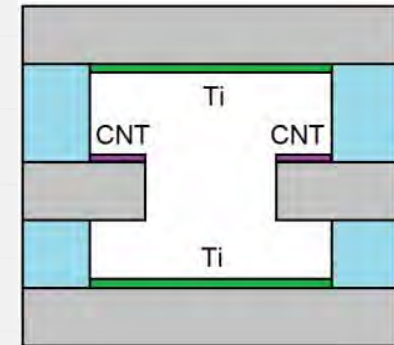
- Gas ionization (electron beam, gas discharge)
- Absorption of ionized particles on getter layer
- Full compatibility and vacuum tightness



Gas ionization in magnetic field

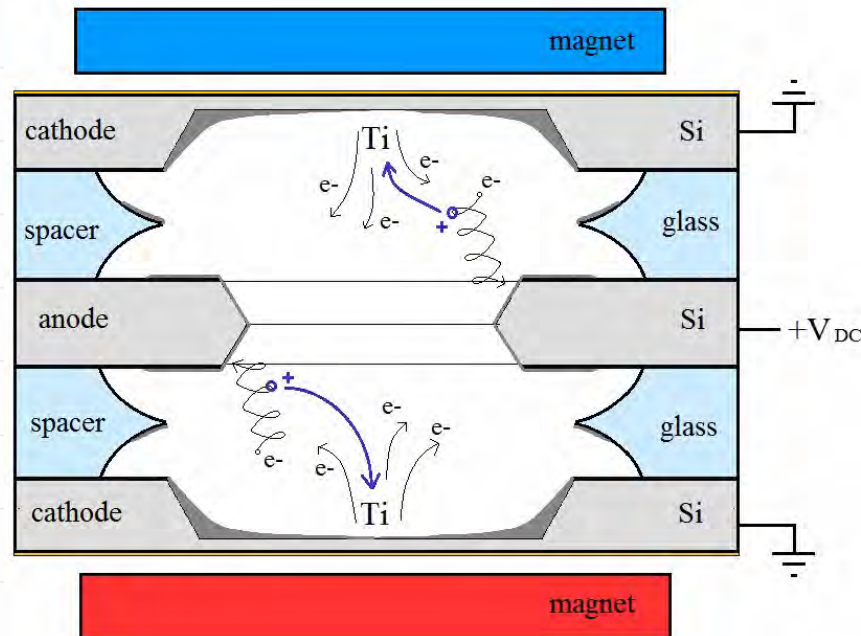


Gas ionization by
an electron
beam emitted
from CNT
cathode

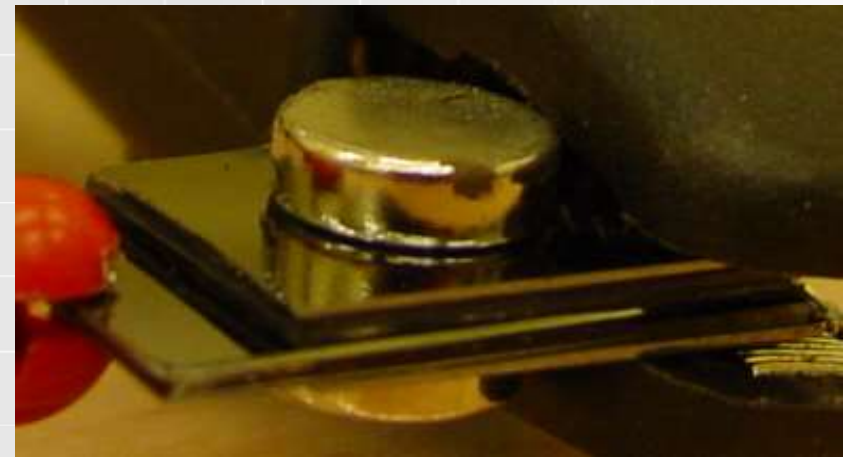




MEMS high vacuum micropump



- Silicon- glass sandwich
- Volume $< 0.01 \text{ cm}^3$
- 2 Nd magnets
- Thin-film getter (optional)

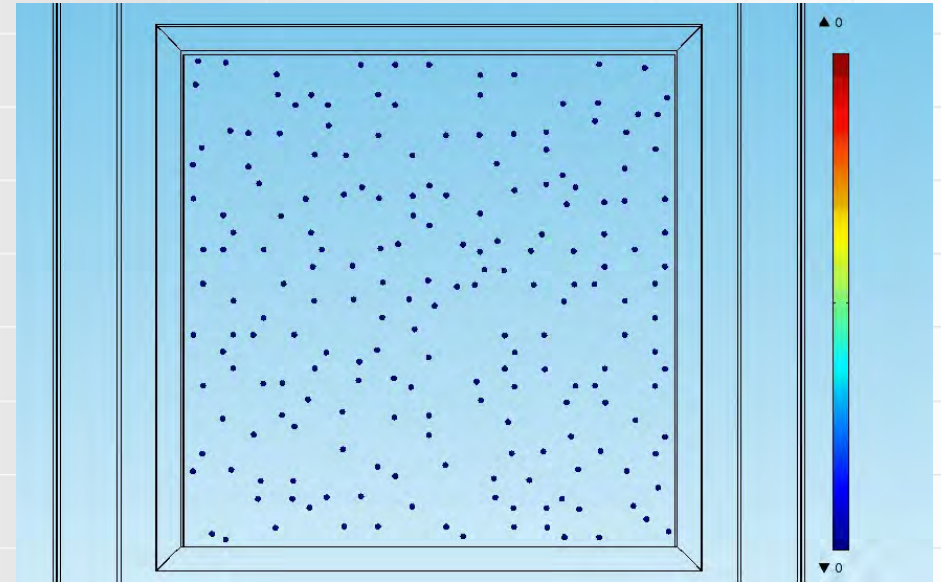
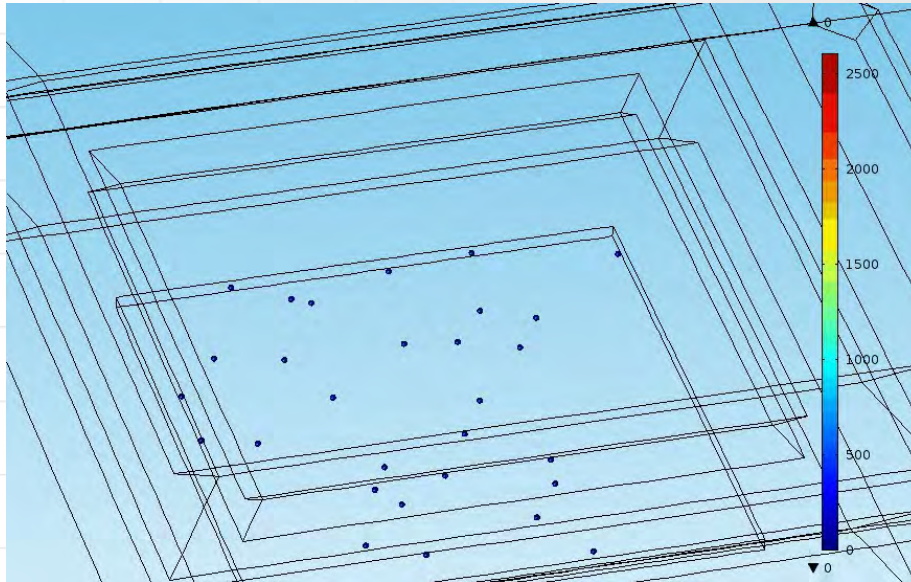


Operating principle:

Ionization process started by spontaneous electrons
Glow-discharge enhanced by external magnetic field
Attraction and adsorption of ions by Ti thin film

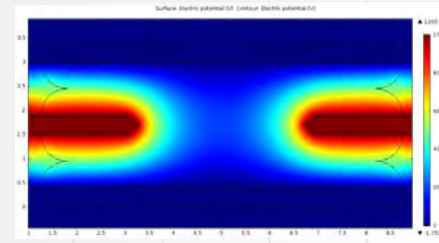
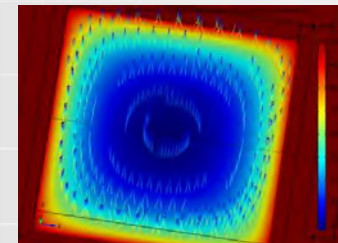


MEMS high vacuum micropump



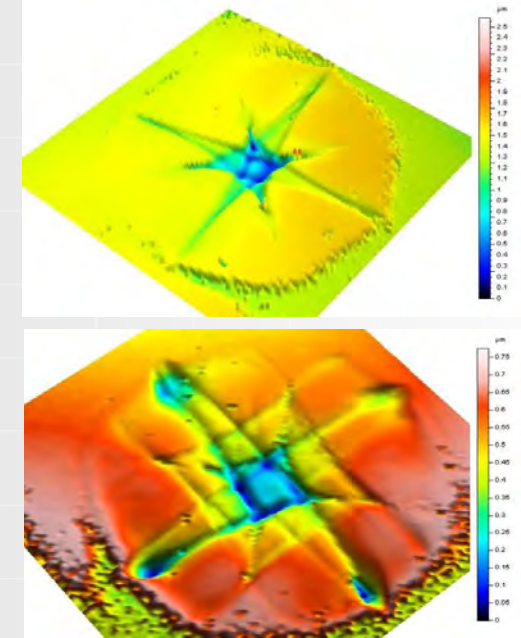
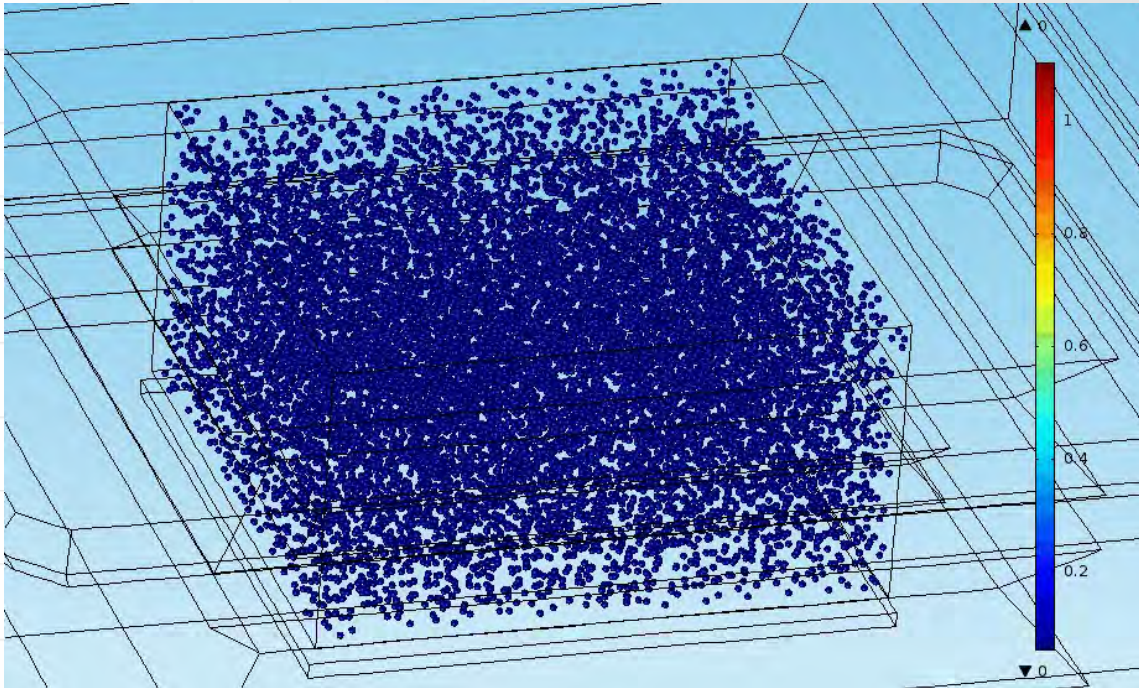
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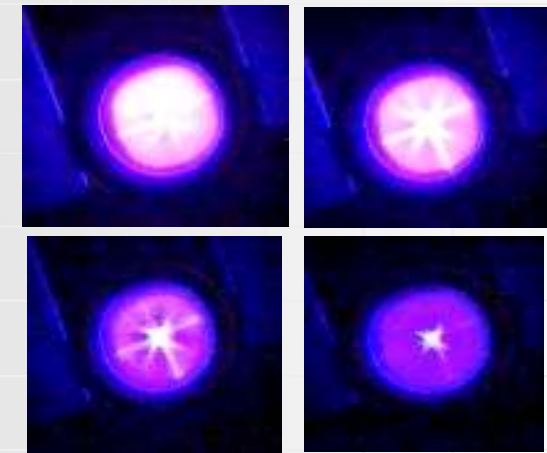


MEMS high vacuum micropump



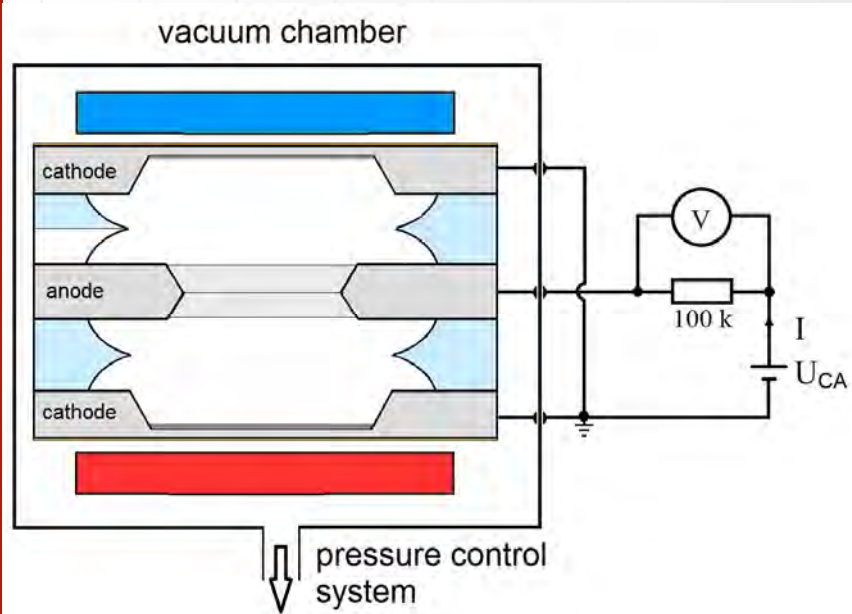
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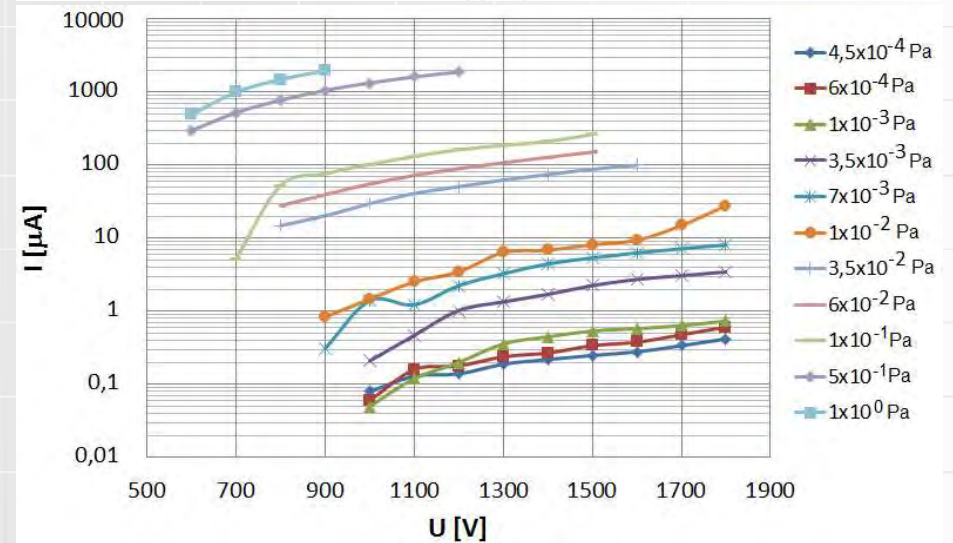
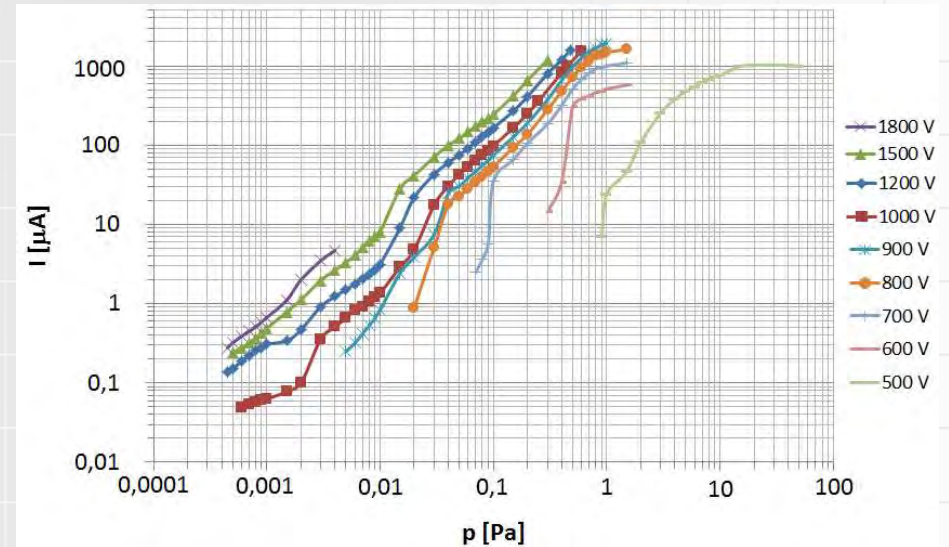




MEMS high vacuum micropump



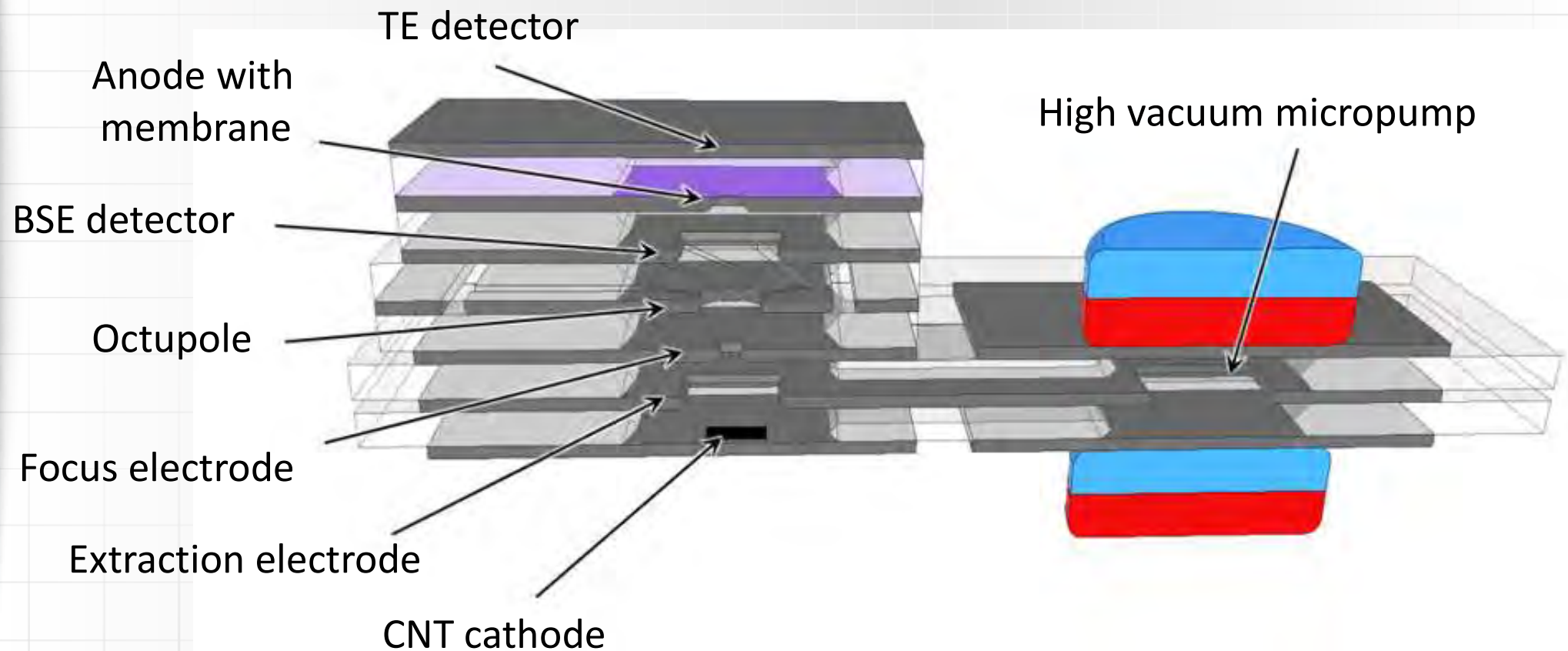
- Operating pressure range:
1 hPa – 10^{-7} hPa
- Operating voltage:
500 – 2500 V





MEMS electron beam microcolumn

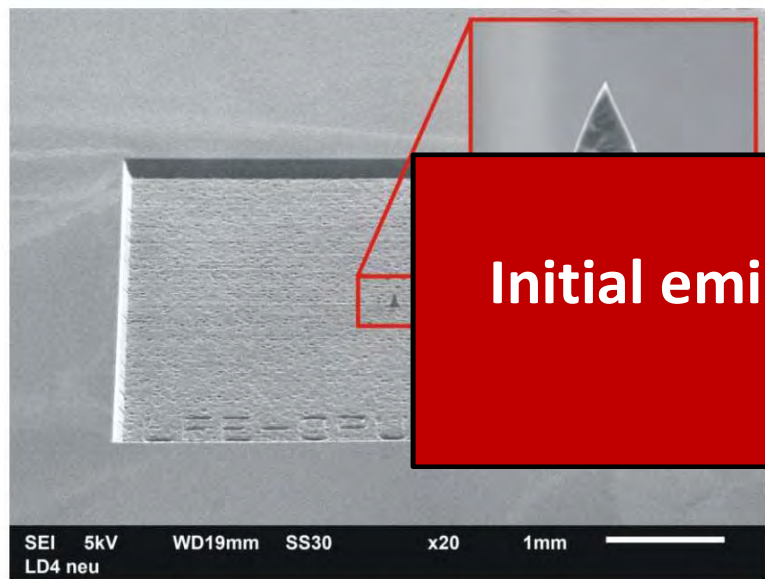
Concept of a MEMS scanning electron microscope





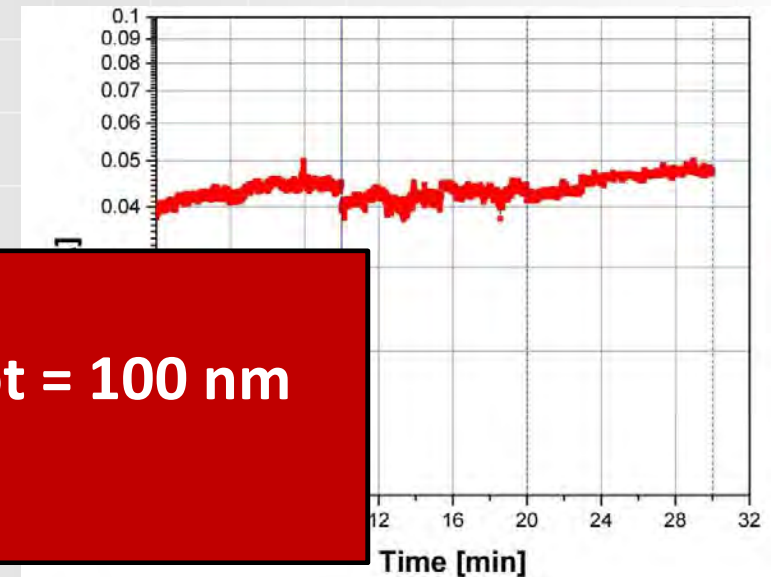
Silicon electron emitter

- Silicon tip fabricated using laser micromachining process (OTH Regensburg)
- Threshold voltage <1500 V
- Small initial spot size (~100 nm)
- Stable current for p-type emitters



P-type silicon tip emitter.

Initial emission spot = 100 nm



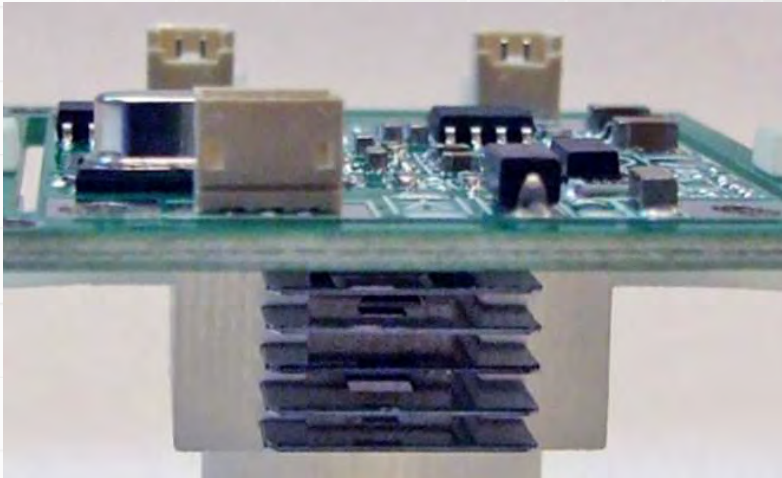
Electron emission current vs. time for p-type silicon emitter

M. Kryzstof, P. Urbański, T. Grzebyk, M. Hausladen, R. Schreiner, MEMS X-ray source: electron emitter development, PowerMEMS 2022, Salt Lake City, Utah, USA, 12 - 15 December 2022, (2022) pp. 248–251.



Focusing of electron beam

- MEMS electrostatic lens (Einzel lens)
- Flat CNT cathode ($1 \times 1 \text{ mm}^2$)
- Silicon gate ($3 \times 3 \text{ mm}^2$)
- LC-1/4 Sony 480TVL Ex-view CCD camera



Electron optics column with CCD camera

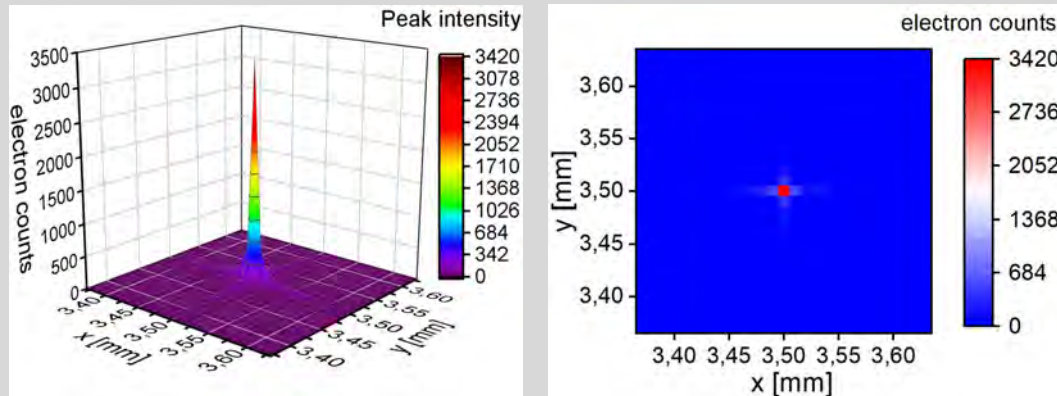




Focusing of electron beam

- Realistic electron beam 50000 electrons from $40 \times 40 \mu\text{m}^2$ area
- 5 different size of Einzel lens were investigated (from 1 to 3 mm)

Sharp silicon/CNT cathode

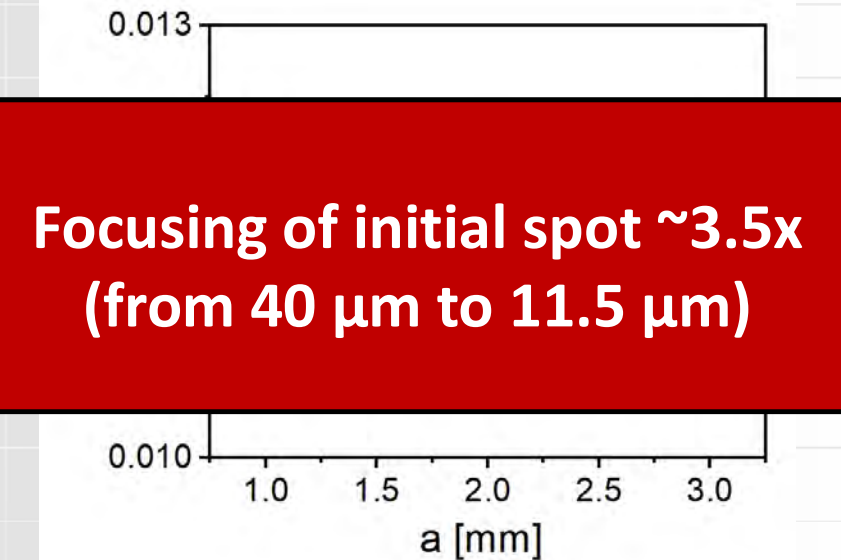


Electron beam spot – $11.5 \mu\text{m}$

Einzel lens size – 3 mm

Focusing voltage – 3590 V

E-beam Energy – 2 keV

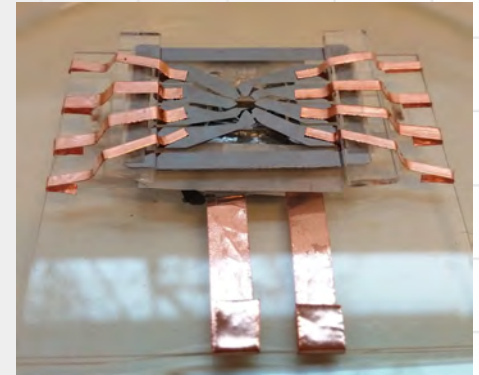


Size of a electron beam spot „D” vs. size of the Einzel lens hole „a”

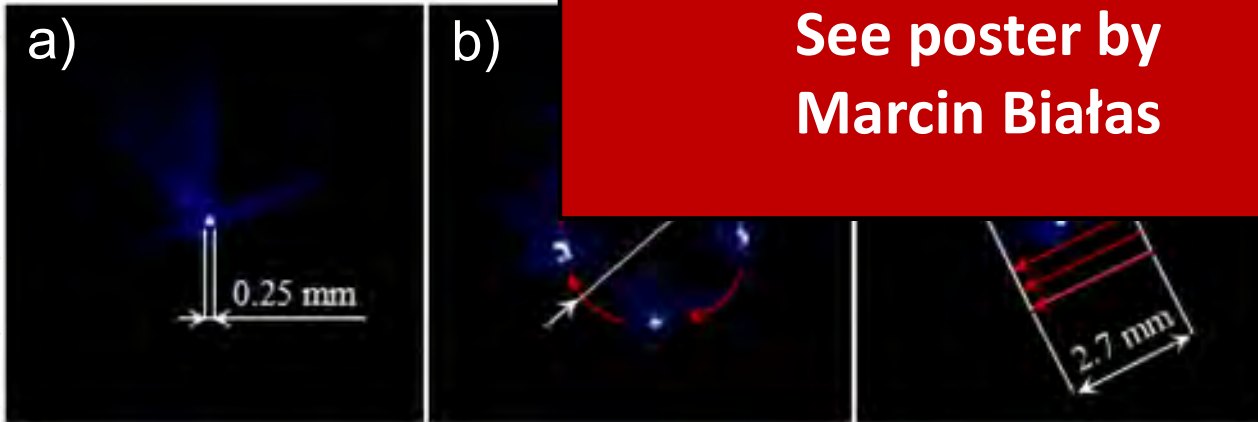


Scanning of the electron beam

- The electron beam is controlled by 8 electrodes (silicon octupole)
- The power supply was designed and made by Marcin Białas
- The **scanning diameter is 3.8 mm**, and the **scanning area is $2.7 \times 2.7 \text{ mm}^2$** with the **scanning sensitivity of $15 \text{ }\mu\text{m/V}$** (for $E = 4 \text{ keV}$, $H = 5 \text{ mm}$)



Silicon-glass octupole mounted on CNT electron gun



Images of the deflected electron beam: a) starting spot of the electron beam, b) deflection along a circular line (electron beam spot in five different positions), c) scanning line by line (red dashed line indicates the movement of the electron beam spot).





Scanning of the electron beam

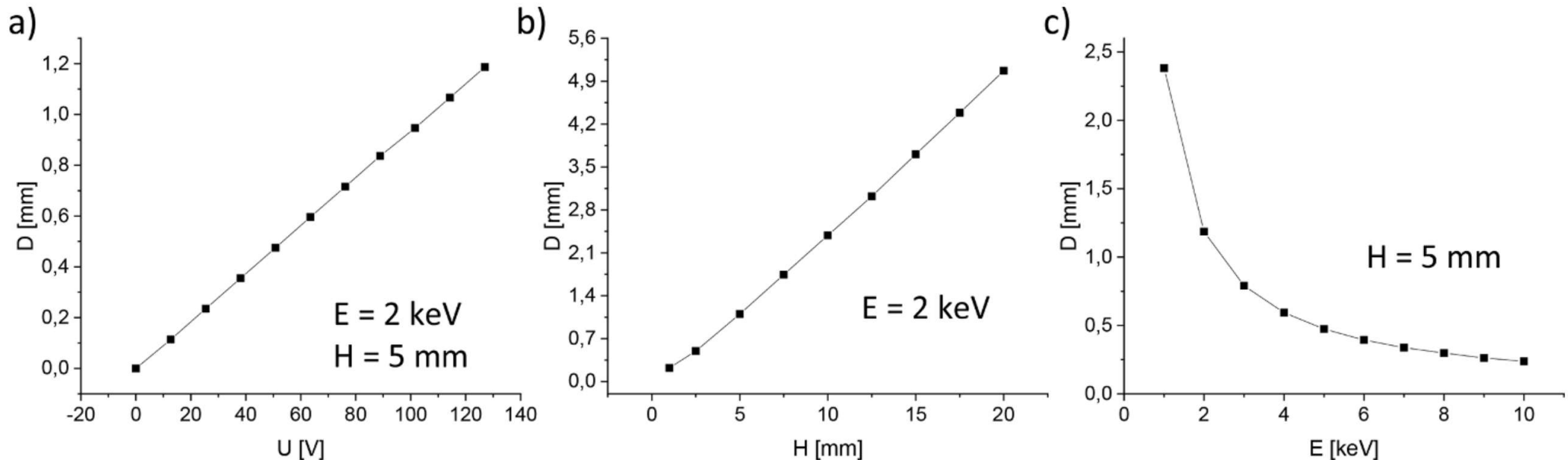
- The scanning area depends on: **octupole voltage**; **working distance** and **electron beam energy**.

$E = 4 \text{ keV}$

$H = 1 \text{ mm}$

$D = 110 \mu\text{m}$

Scanning step = 27 nm

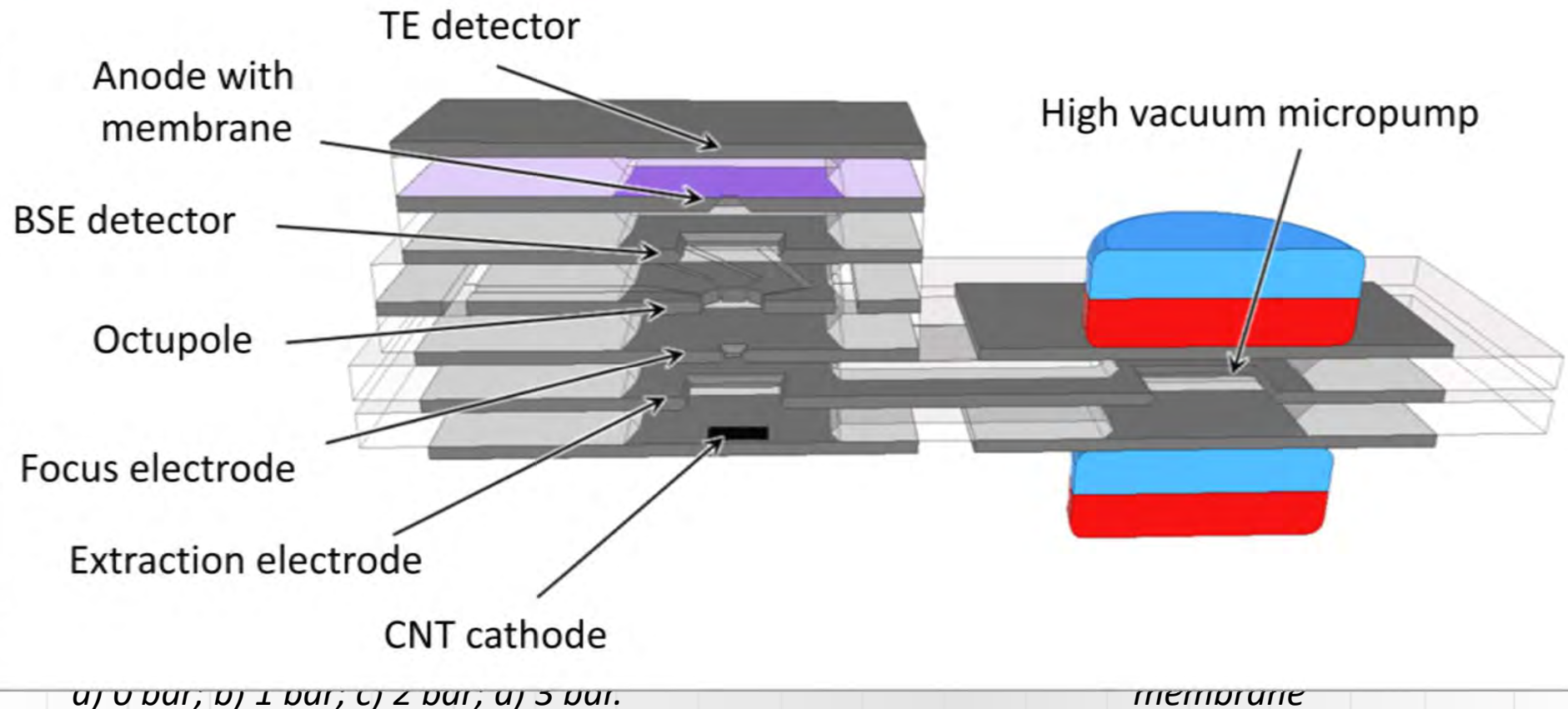


*The dimension of scanning area as a function of: a) octupole voltage ($\pm 127 \text{ V}$),
b) octupole-observation plane distance, c) electron beam energy*



MEMS electron beam microcolumn

Concept of a MEMS scanning electron microscope

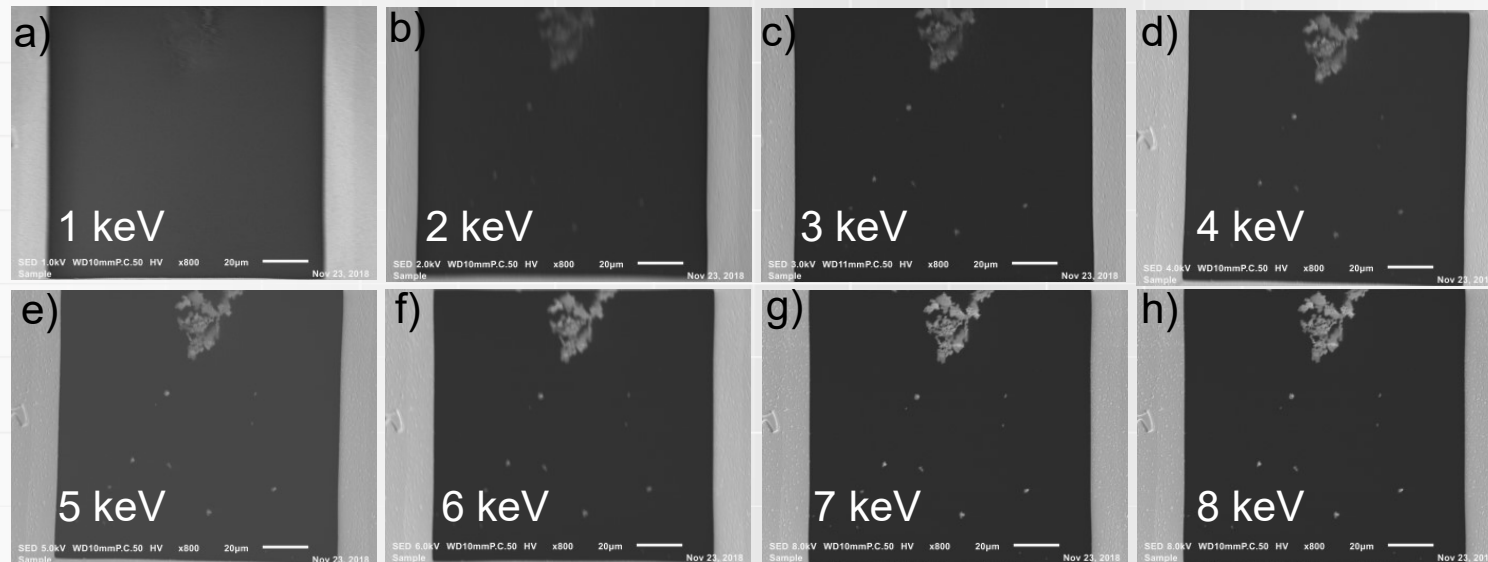
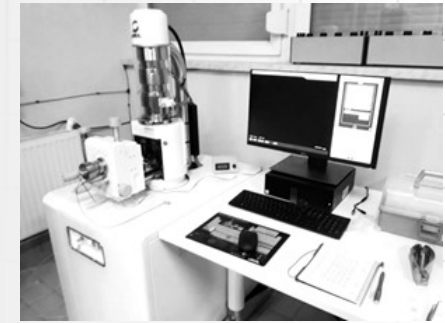




Imaging samples through the Si_3N_4 membrane with low energy electron beam

NaCl – salt crystals

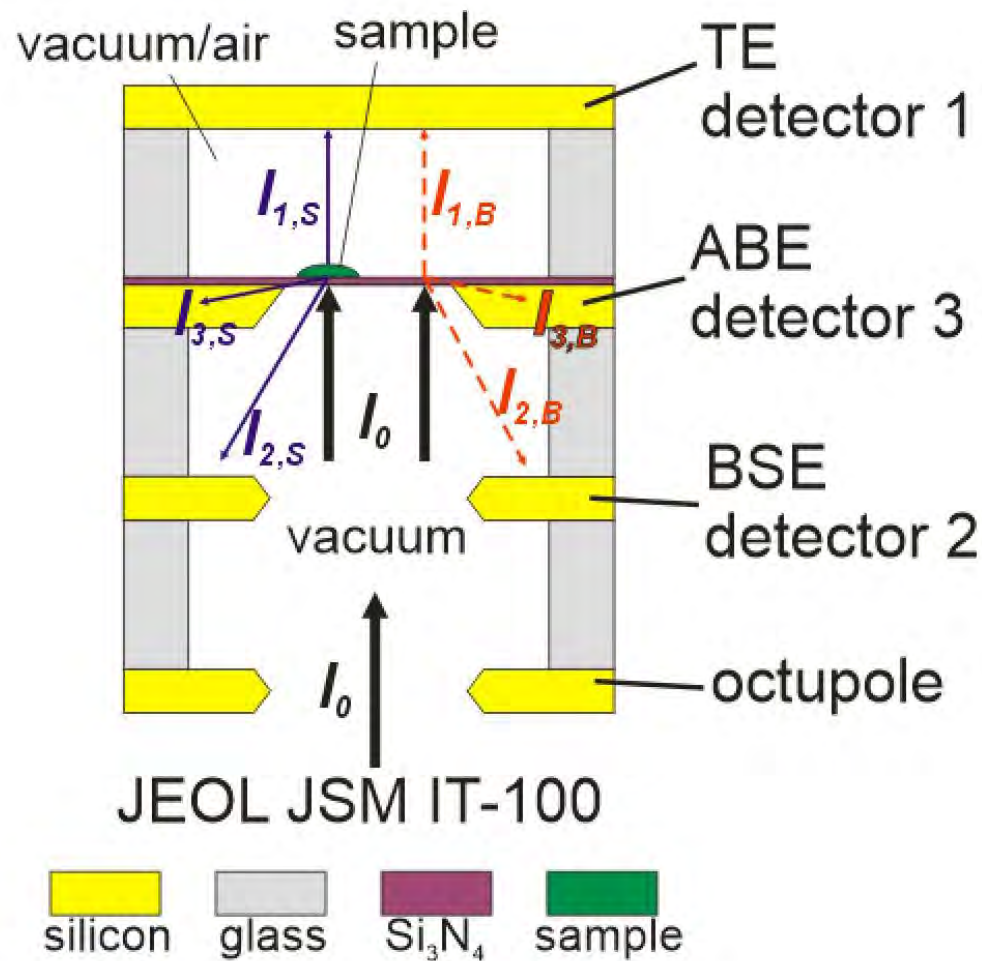
JEOL JSM IT-100



Secondary electron images of salt crystals (NaCl) through Si_3N_4 membrane (50 nm thick) for electron beam energies of: a) 1 keV, b) 2 keV, c) 3 keV, d) 4 keV, e) 5 keV, f) 6 keV, g) 7 keV, h) 8 keV.



New detectors for MEMS SEM



Silicon electron collectors:

- TE – transmitted electrons
- ABE – absorbed electrons
- BSE – backscattered electrons
- **I_S – sample current**
(electrons collected at the detector after interacting with the sample)
- **I_B – background current**
(electrons collected at the detector with no interaction with the sample)
- **ΔI = |I_S - I_B| – image contrast**



Testing of the detectors

	Detector 1 Transmitted electrons	Detector 2 Reflected electrons	Detector 3 Absorbed electrons	Sample/conditions	Color bar indicating the value of ADC bits (0..1023) in [%] 0% 50% 100%
$E_0 = 3 \text{ keV}$ $I_0 = 0.85 \text{ nA}$				hexagonal grid high vacuum membrane	
$E_0 = 5 \text{ keV}$ $I_0 = 1.09 \text{ nA}$				steel particles (5-30 μm) high vacuum membrane	
$E_0 = 7 \text{ keV}$ $I_0 = 1.46 \text{ nA}$				steel particles (5-30 μm) high vacuum/ air membrane	

All three detectors work



JEOL JSM IT-100 vs. MEMS EM

- The resolution of the MEMS EM for TE detector is comparable with commercial SEM (for low magnification)

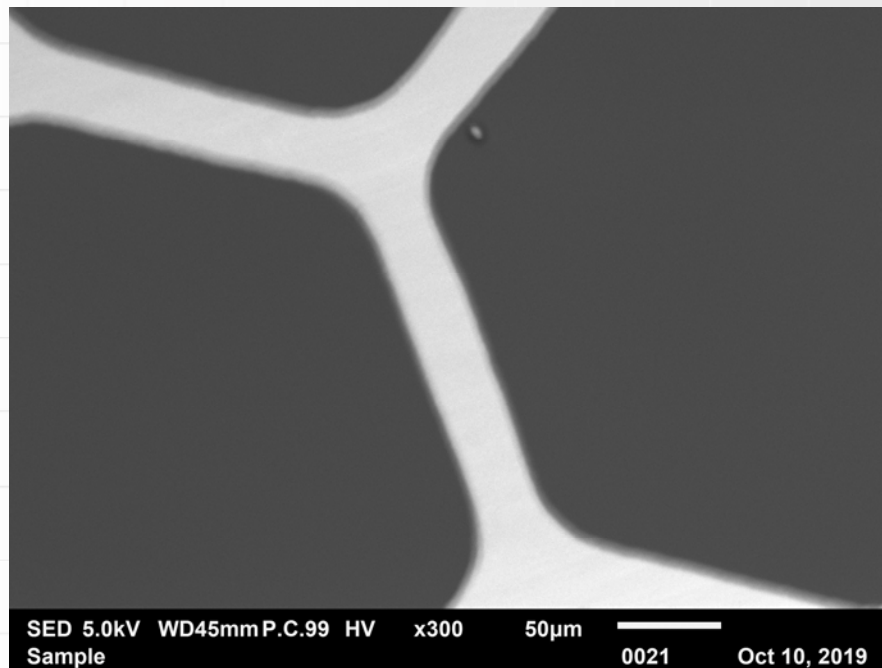


Image of a metal grid with the use of JEOL JSM IT-100

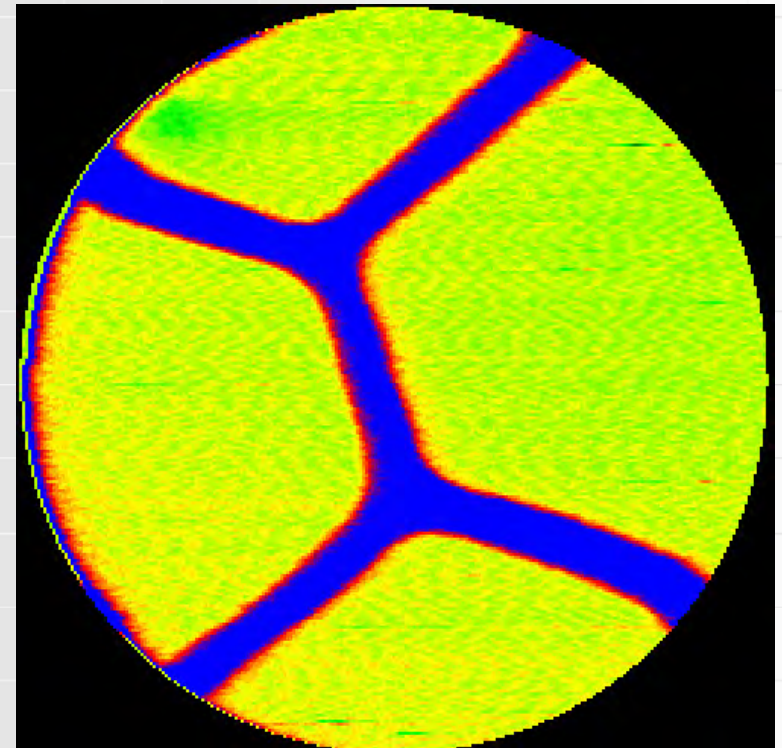


Image of the metal grid with the use of MEMS TEM



JEOL JSM IT-100 vs. MEMS EM

- With higher magnification the resolution and quality is worse due to noise

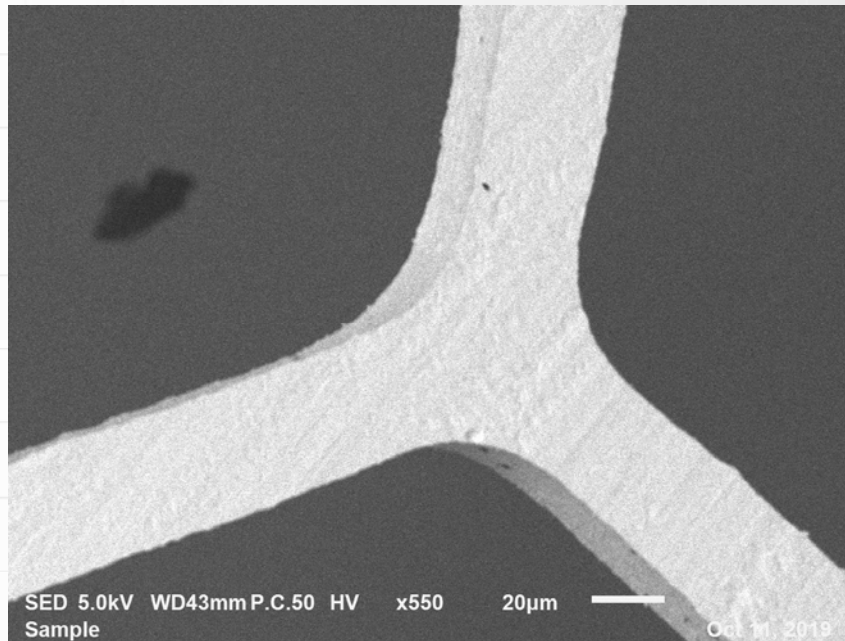


Image of a metal grid with the use of JEOL JSM IT-100

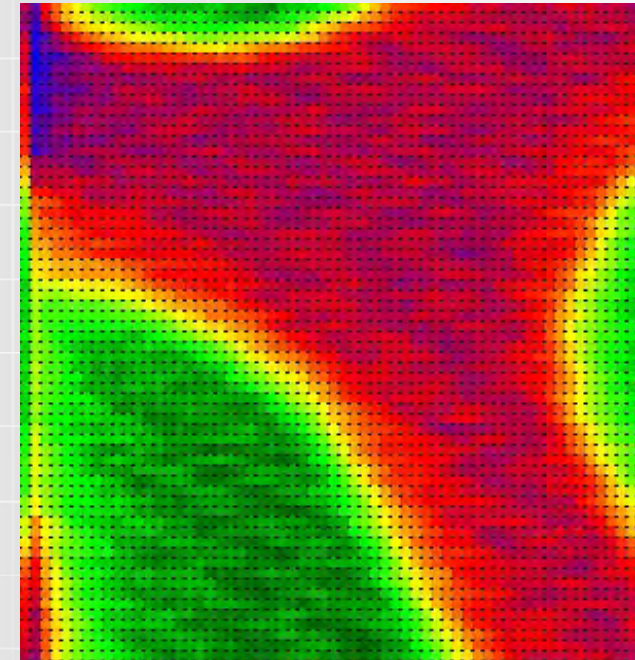


Image of the metal grid with the use of MEMS TEM



JEOL JSM IT-100 vs. MEMS EM

- The field of view of the MEMS TEM is smaller thus the image distortion

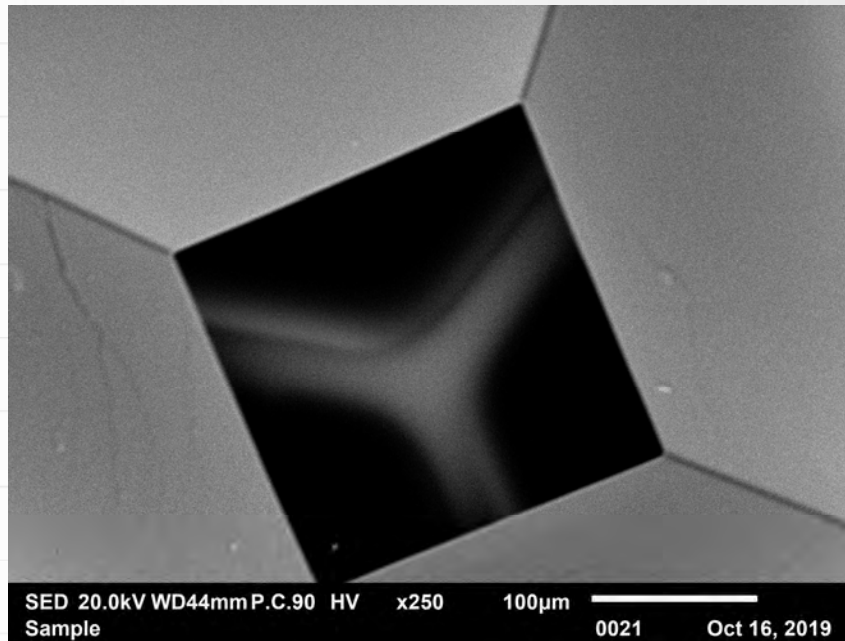


Image of a metal grid through the membrane with the use of JEOL JSM IT-100

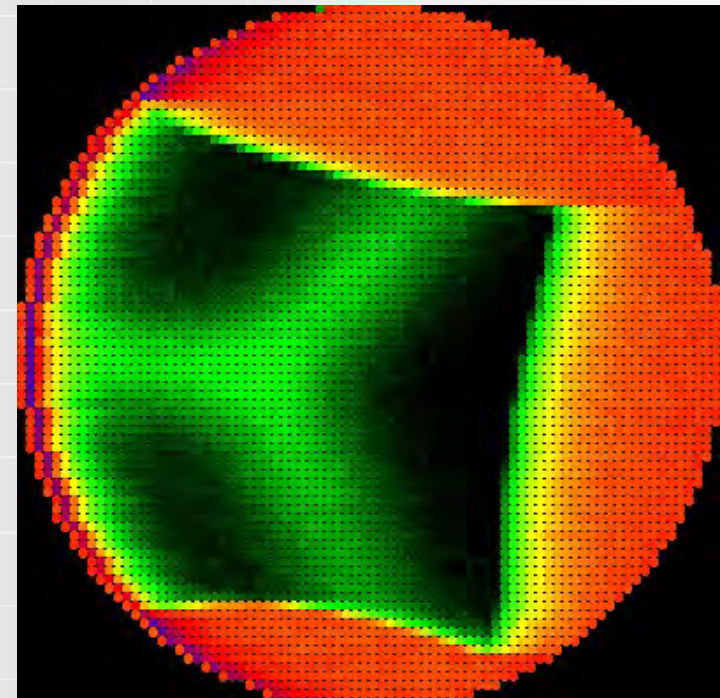


Image of the metal grid through the membrane with the use of MEMS TEM

Imaging using MEMS SEM test model

- Test structure inside high vacuum chamber (10^{-5} mbar)
- The metal grid as an electron collector
- High fluctuations of electron emission visible at the image

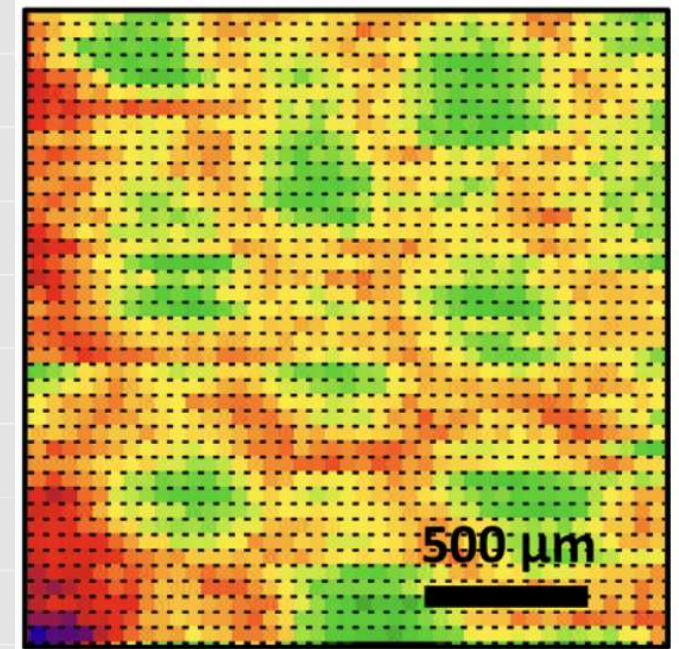
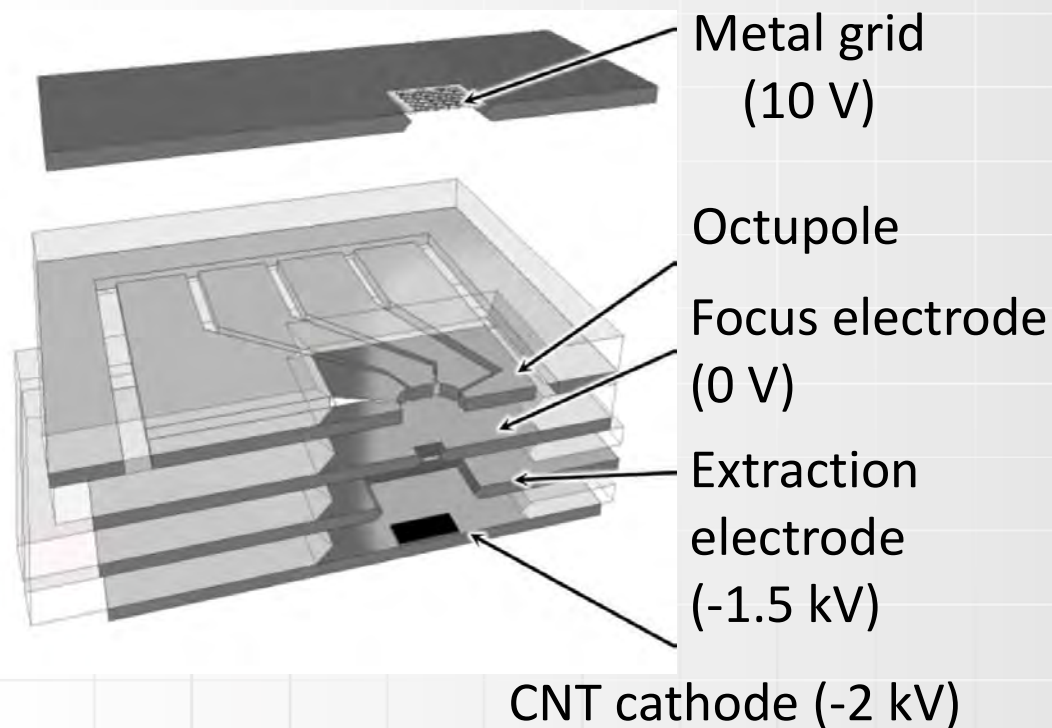
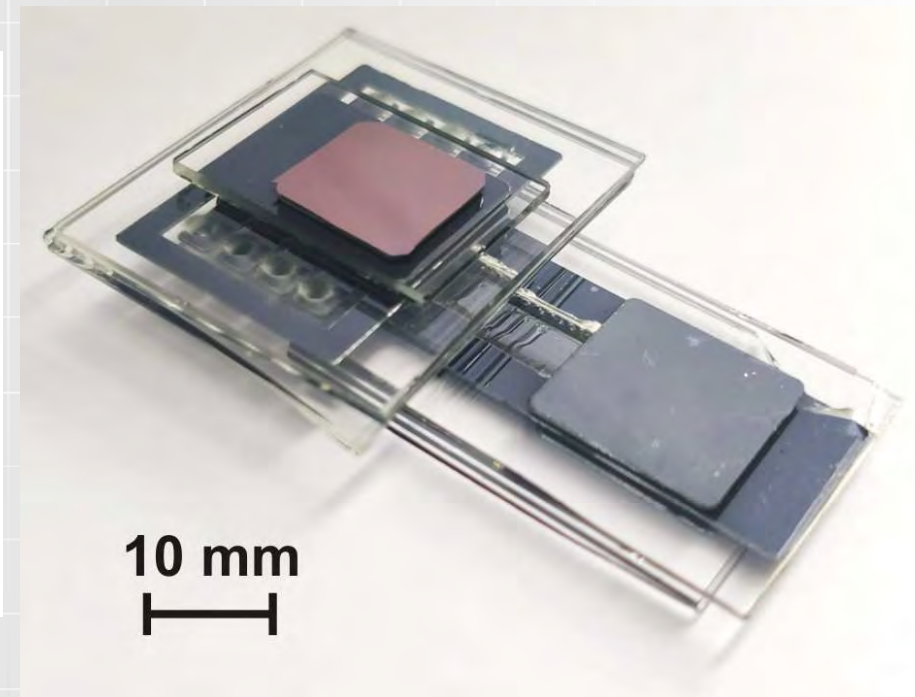
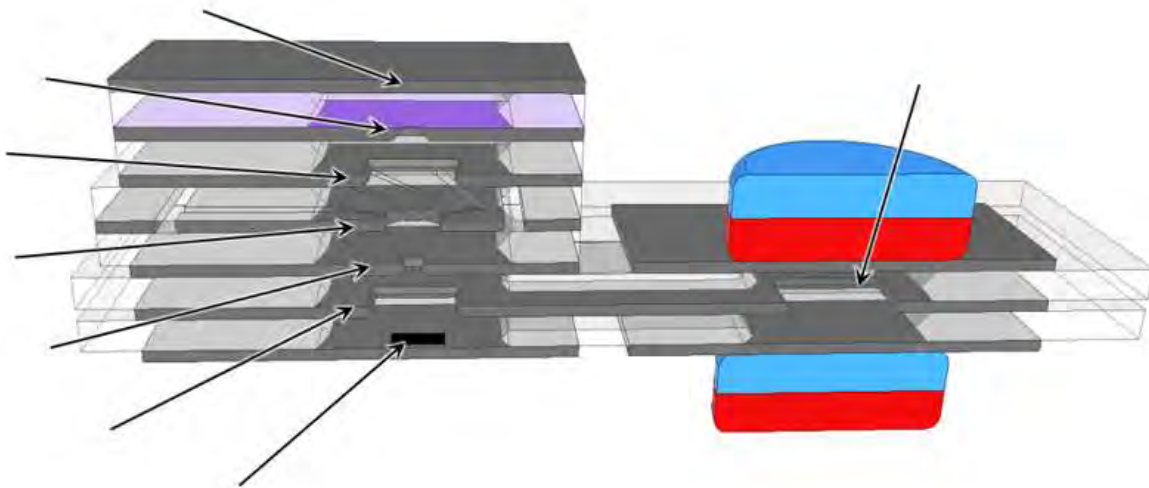


Image of a hexagonal metal grid



First in the world model of MEMS SEM

1. At this point all elements of MEMS SEM are tested and operational
2. New detection methods were developed and tested



** - assuming 100 nm initial spot and 3.5 times focusing.

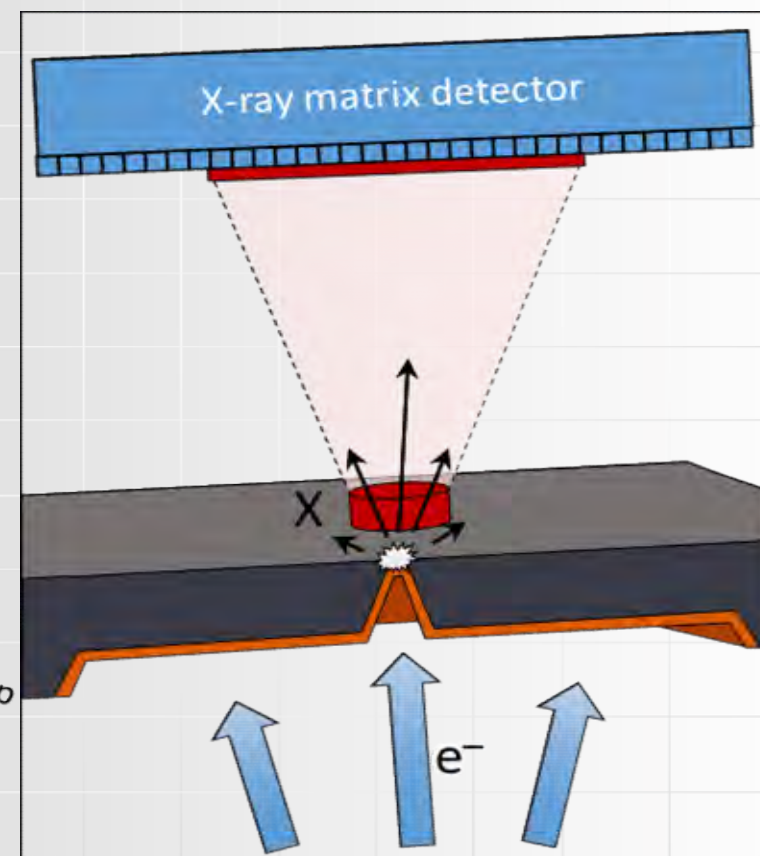
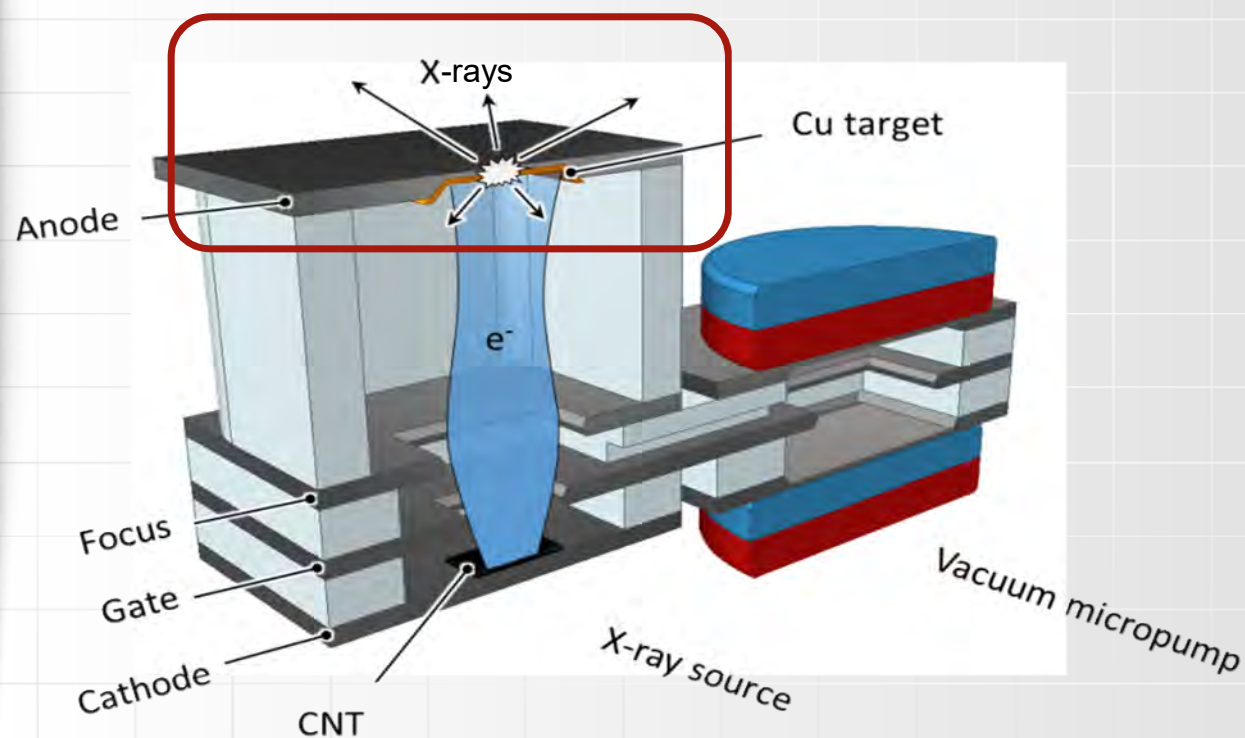
*** - counting external dimensions of the device.



MEMS electron beam microcolumn

Concept of a MEMS point X-ray source

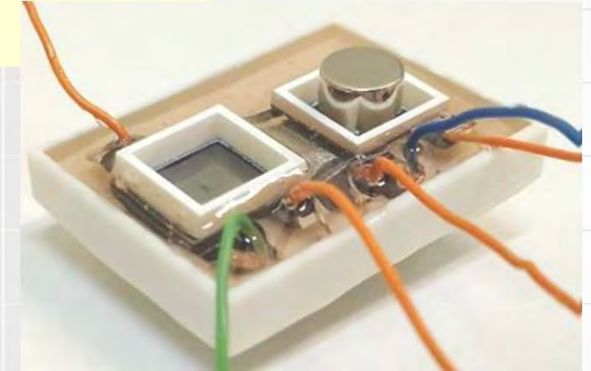
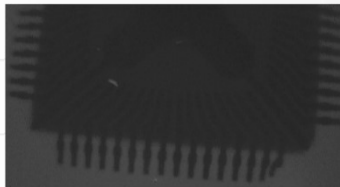
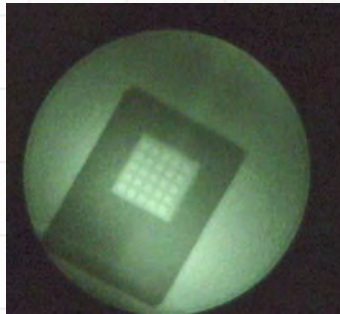
Integration of: micropump, electron optics column, and thin target on a single chip





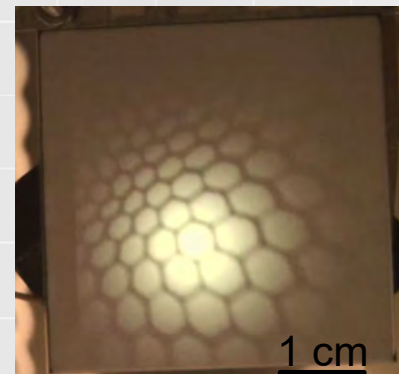
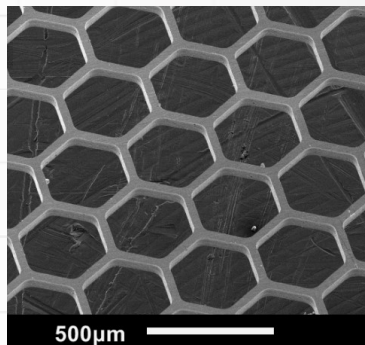
Fully MEMS X-ray source

Inspection of small objects



**See poster by
Paweł Urbański**

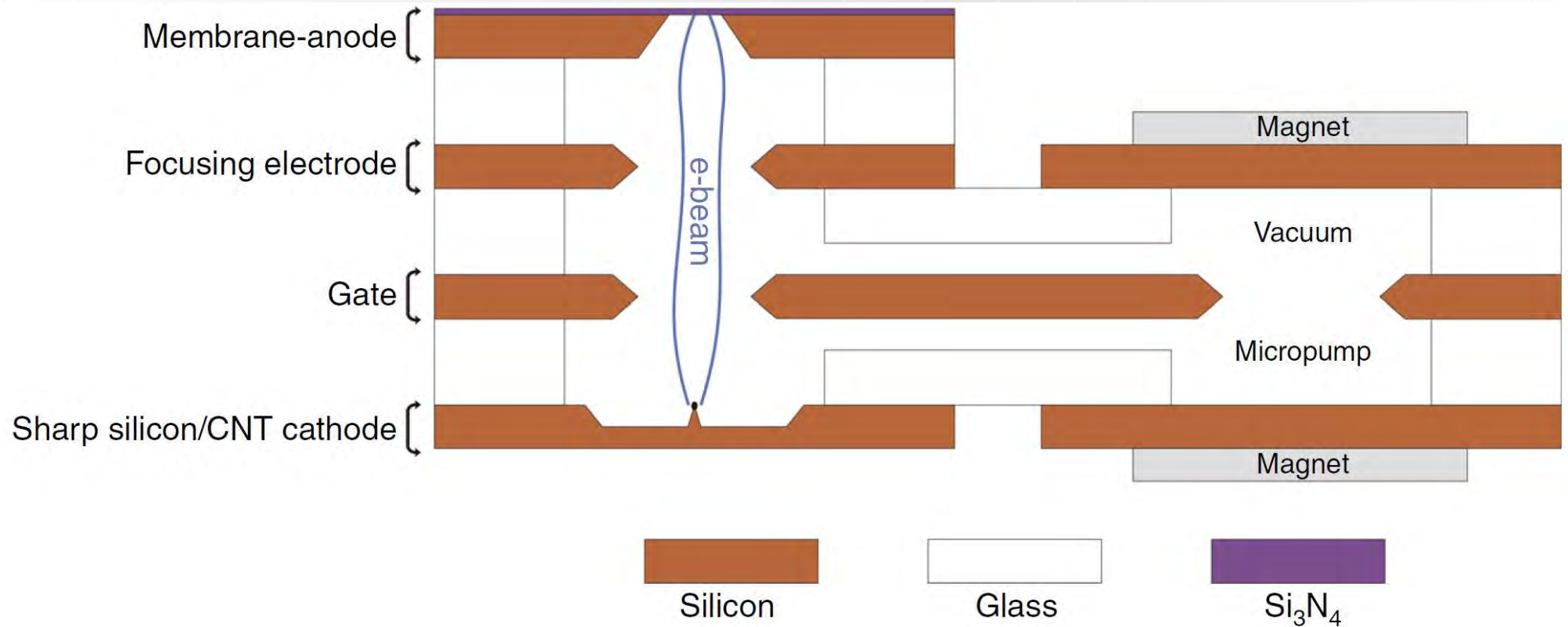
Object magnification



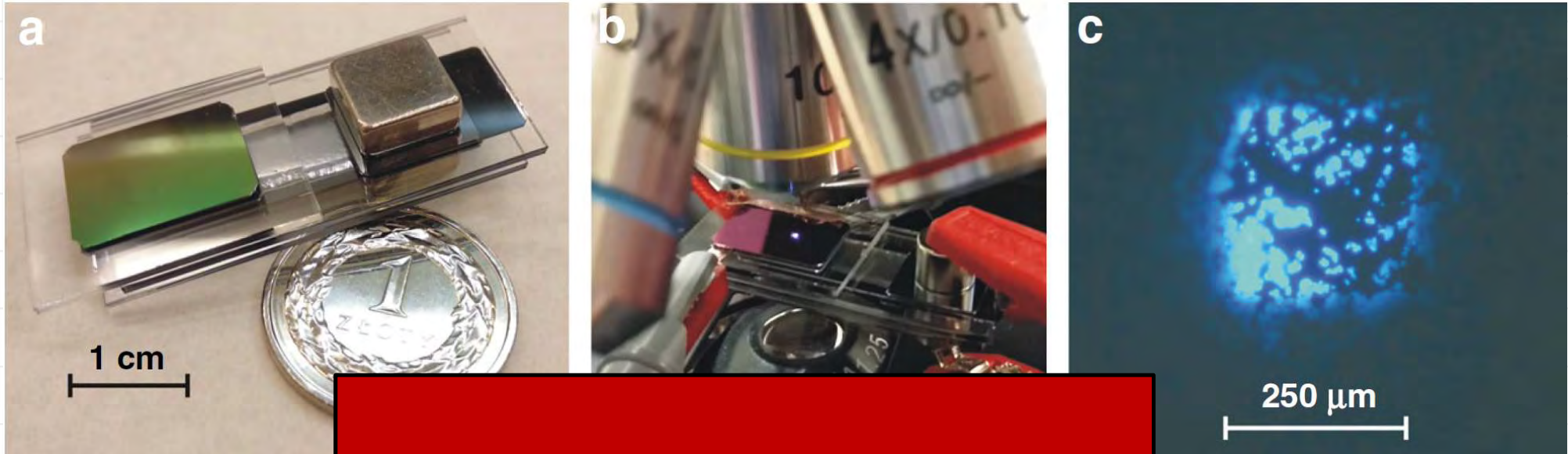
MEMS electron beam microcolumn

Concept of a MEMS electron source

Structure similar to X-ray source. Anode with thin silicon nitride membrane.



MEMS electron source



See poster by
Michał Zychla and Jan Sobków

- Operates in air
- Generates electron beam that passes to air
- Cathodoluminescence investigation of materials for pharmaceutical industry/geology
- Studies of electron interactions with biological samples or DNA



MEMS electron beam microcolumn

Concept of a MEMS free electron laser

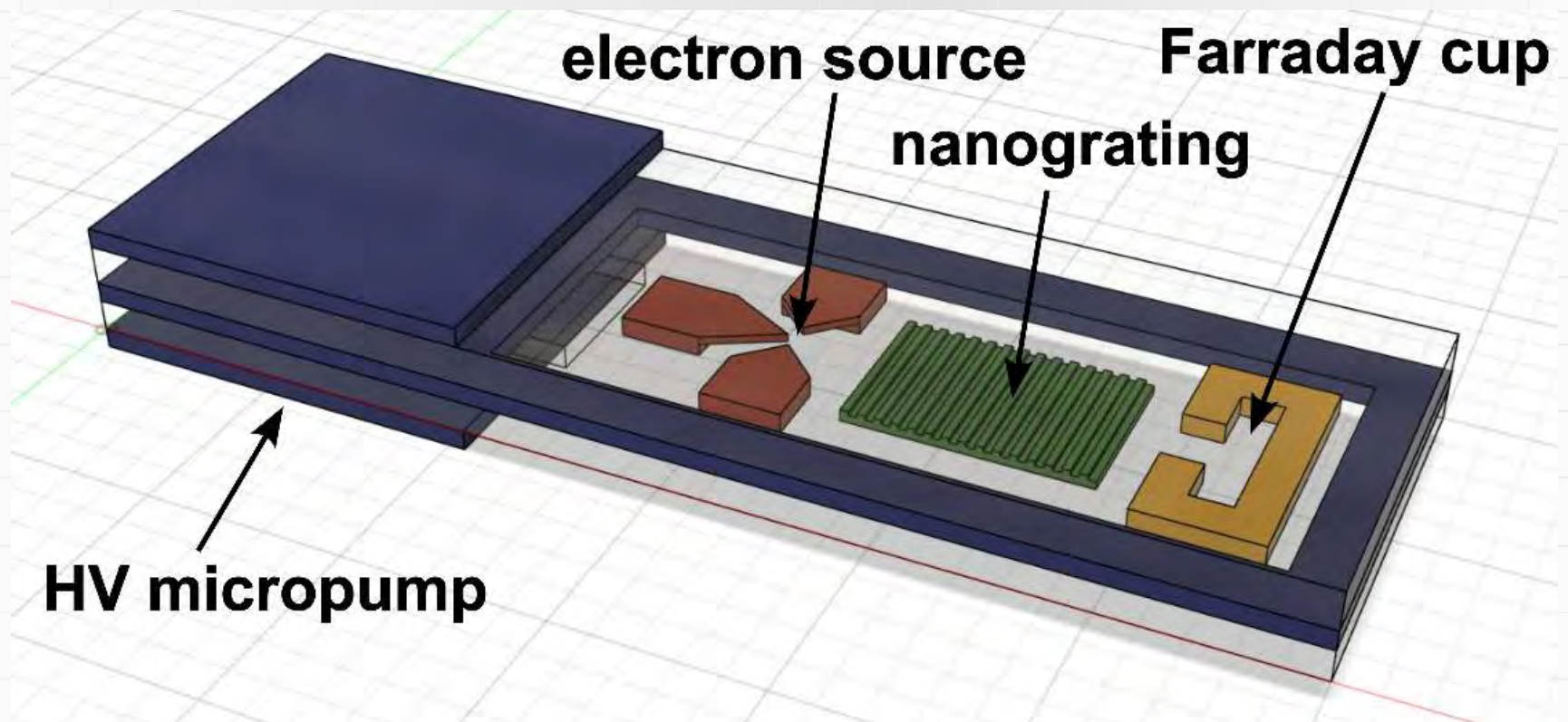


Diagram of the general electron laser proposed by Haid et al. (2004) (original drawing)



Summary

VACUUM-SEALED ELECTRON BEAM MICROCOLUMN

1. MEMS technology ideal for integrating elements of electron optical devices on-chip
2. MEMS high vacuum pump generates up to 10^{-7} mbar vacuum
3. Anodic bonding technique enables vacuum sealing of the device
4. MEMS SEM elements developed and tested
5. MEMS X-ray source operational
6. MEMS electron source operational
7. MEMS FEL – conceptual vision



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Thank you for your attention

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